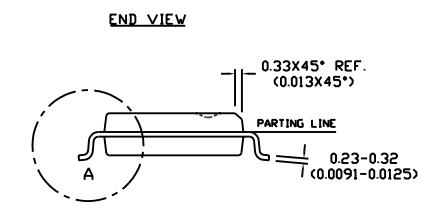
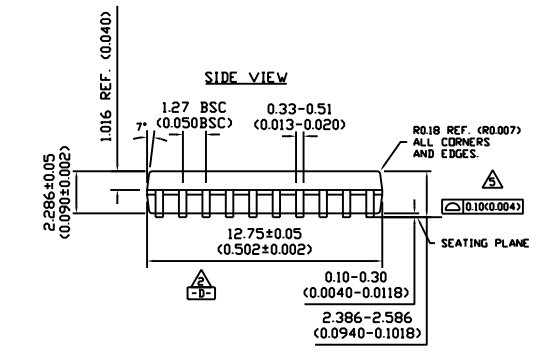
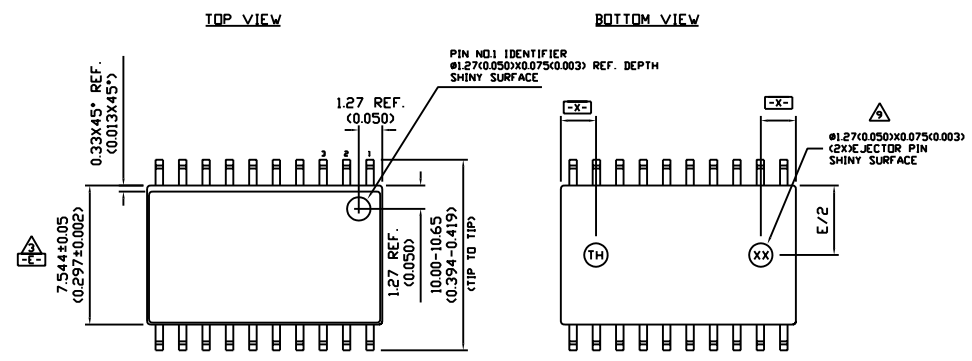
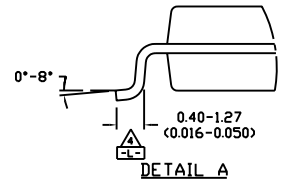



REV	DESCRIPTION	DATE
A	ORIGINAL ISSUE	JUN 30'00



- NOTES
1. DIMENSIONING & TOLERANCING PER ANS Y14.5M-1982
  2. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED 0.15 MM (0.006") PER SIDE.
  3. DIMENSION "E" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM (0.010") PER SIDE.
  4. "L" IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTATE.
  5. FORMED LEADS SHALL BE PLANED WITH RESPECT TO ONE ANOTHER WITHIN 0.10 MM (0.004") AT SEATING PLANE.
  6. BODY FINISH : 21 - 24 CHARMILLES.
  7. CONTROLLING DIMENSION : MILLIMETER CONVERTED INCH ARE NOT NECESSARILY EXACT.
  8. LEAD FINISH WILL BE ELECTROPLATING WITH A THICKNESS OF 300-800 MICROINCHES.
  9. CHARACTER HEIGHT ON EJECTOR PIN IS 0.635MM(0.025")  
"TH" IS STAND FOR THAILAND  
"XX" IS STAND FOR MOLD CAVITY NUMBER.(01,02,03,.....99)
  10. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.05MM(±0.002")
  11. RAISED CHARACTER NOT TO PROTRUDE BEYOND SURFACE OF PACKAGE BODY.
  12. THE LEAD WIDTH, AS MEASURED 0.36MM(0.014") OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAX. VALUE OF 0.61MM(0.024")

DIM "X" 1.90(0.075) OR 3.17(0.125)



 <b>HANA</b>	DRAWN BY: ANUPHAB U.	TITLE: 20L SOIC PKG. OUTLINE DWG. 300 MIL BODY WIDTH FAMILY (MGP MOLD)		
	CHECKED BY: NATAPORN C.	DATE : JUN 30'00	REF. NO. : JEDEC MS-013	SCALE : NDT TO SCALE
APPROVED BY: THANAPONG I.	DWG. NO. <b>J020P0-01</b>		REV. A	SHEET 1 OF 1
APPROVED BY: VIRAT T.				